

# SOT190-2

plastic very small outline package; 56 leads; face down

8 February 2016

Package information

## 1. Package summary

Terminal position code	D (double)
Package type descriptive code	VSO56
Package type industry code	VSO56
Package style descriptive code	VSO (very thin small outline)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	19-2-2003

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		21.35	-	21.5	21.65	mm
E	package width		11	-	11	11.1	mm
A	seated height		[tbd]	-	3.3	3.3	mm
A <sub>2</sub>	package height		2.8	-	2.85	3	mm
n <sub>2</sub>	actual quantity of termination		-	-	56	-	



2. Package outline

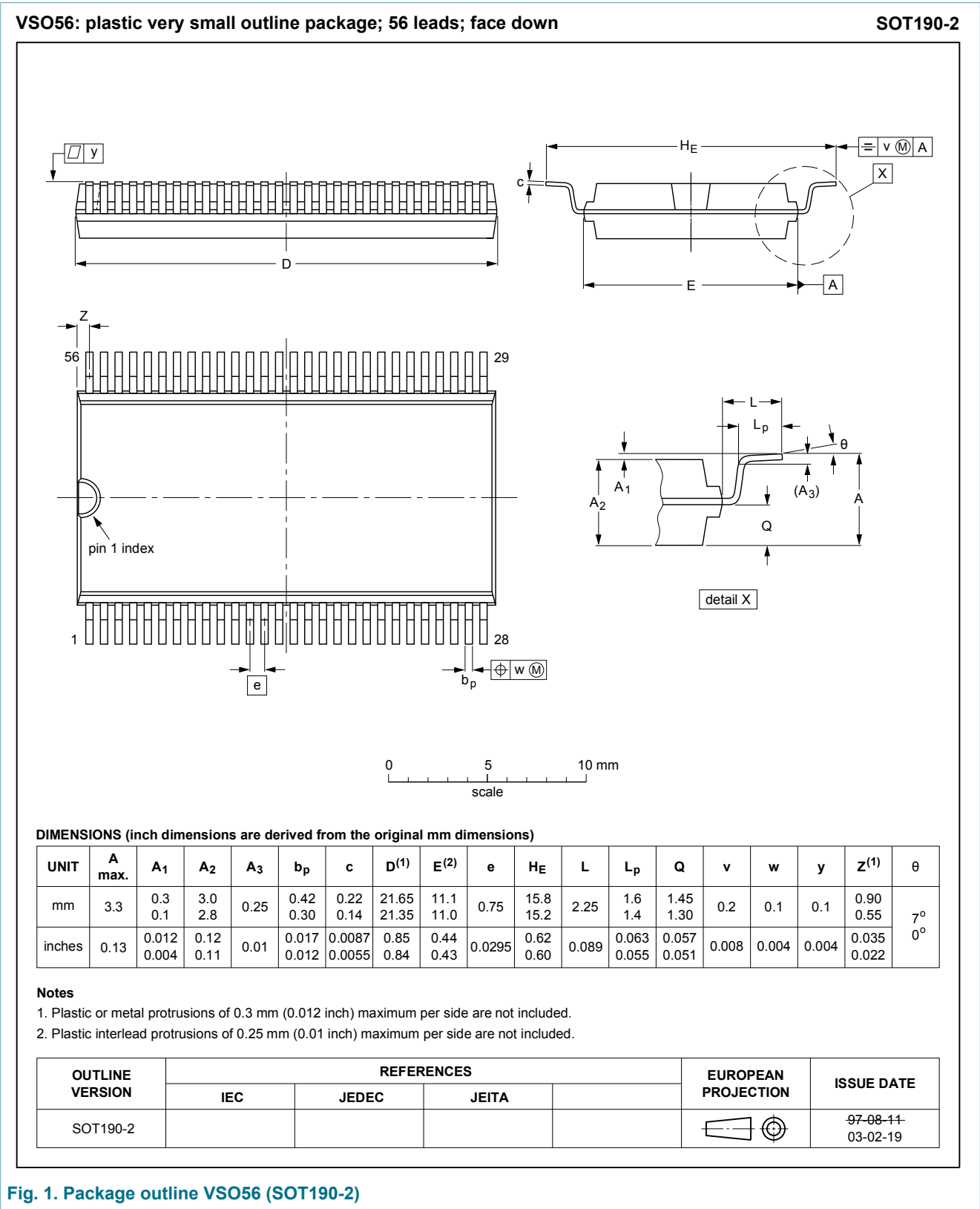


Fig. 1. Package outline VSO56 (SOT190-2)

3. Soldering

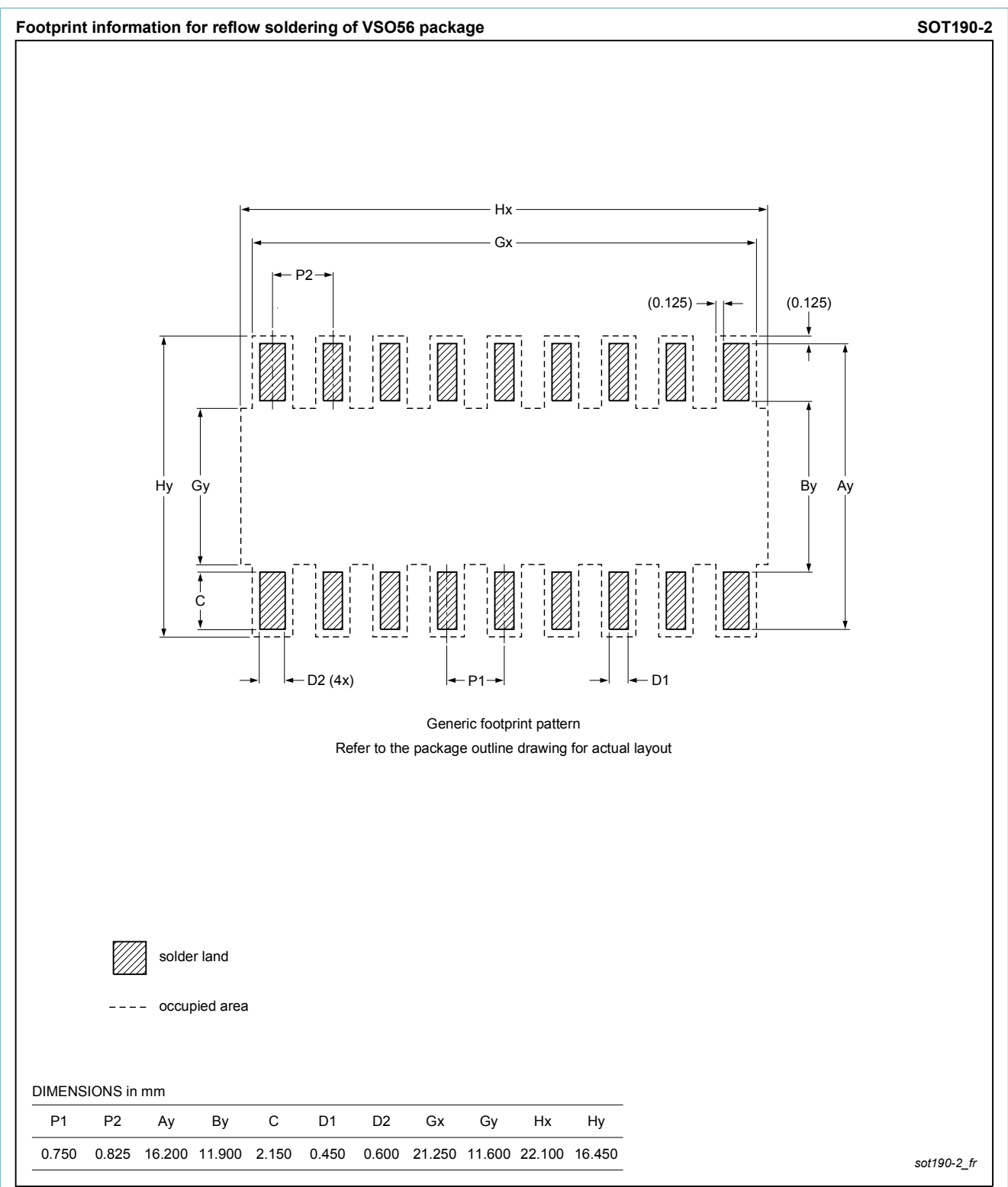
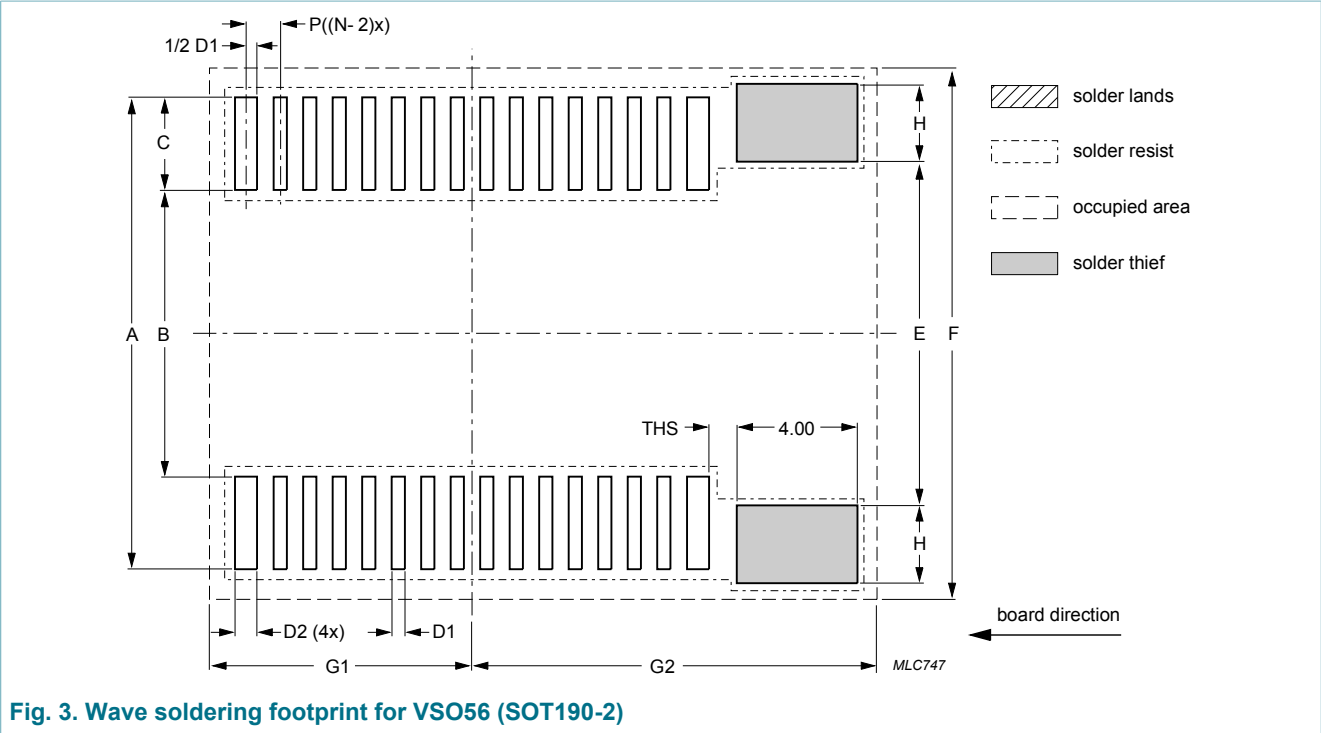


Fig. 2. Reflow soldering footprint for VSO56 (SOT190-2)

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## 4. Legal information

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5. Contents

1. Package summary..... 1

2. Package outline..... 2

3. Soldering..... 3

4. Legal information..... 5

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